



3D Printing Functionality: Materials, Sensors, Electromagnetics

Guest Editor:

Prof. Dr. Corey Shemelya

Department of Electrical and
Computer Engineering, University
of Massachusetts Lowell, Lowell,
MA 01854, USA

Deadline for manuscript
submissions:

closed (15 May 2021)

Message from the Guest Editor

Recently, there has been a rise in the commercial, industrial, and academic interest in the rapid prototyping technology, commonly referred to as additive manufacturing and 3D printing. Traditionally, additive technologies have been limited to purely mechanical applications. However, in recent years there has been a surge in advanced manufacturing investigations ranging from printed sensors and antennas to chemical and thermal functional materials. This additional functionality, incorporated with the ease and speed of traditional additive techniques, has the potential to revolutionize the production processes. It is expected that advances in functional printing techniques will drastically reduce time-to-market as well as improve overall device functionality.

As such, this Special Issue is intended to examine new techniques, designs, and processes that improve the functionality of printable and 3D printable devices or material systems. Of particular interest are topics that incorporate multiple means of functionality, whether through mechanical, thermal, electromagnetic, electrical, or chemical means.





an Open Access Journal by MDPI

Editor-in-Chief

Prof. Dr. Joshua M. Pearce

Department of Electrical &
Computer Engineering, Western
University, London, ON N6A 3K7,
Canada

Message from the Editor-in-Chief

Designs (ISSN 2411-9660) is a peer-reviewed and open access journal which provides a unifying research framework for a wide range of engineering designs of disciplines and industrial applications, including mechanical engineering, electrical engineering, civil engineering, mechatronics, aerospace engineering, bioengineering, energy engineering, industrial engineering and manufacturing systems are of interest. We would like to invite you to contribute to the journal by sending us your high quality research papers. We would be pleased to welcome you as one of our authors.

Author Benefits

Open Access: free for readers, with article processing charges (APC) paid by authors or their institutions.

High visibility: indexed within Scopus, Inspec, and other databases.

Journal Rank: CiteScore - Q2 (*Engineering (miscellaneous)*)

Contact Us

Designs Editorial Office
MDPI, St. Alban-Anlage 66
4052 Basel, Switzerland

Tel: +41 61 683 77 34
www.mdpi.com

mdpi.com/journal/designs
designs@mdpi.com